

HEAT-RESISTANT POLY-ALPHA, ALPHA-DIFLUORO-PARAXYLYLENE FILM**Publication number:** JP10195181**Publication date:** 1998-07-28**Inventor:** MARUYAMA HIROSHI**Applicant:** DAISAN KASEI KK**Classification:**

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C08G61/00; C23C16/00

- european:**Application number:** JP19970017616 19970114**Priority number(s):** JP19970017616 19970114**Report a data error here****Abstract of JP10195181**

PROBLEM TO BE SOLVED: To obtain a highly heat-stable heat-resistant poly- α , α -difluoro-paraxylylene film through polymerization by chemical vapor deposition by using a synthesized tetrafluoro-[2,2]-paracyclophane as the starting material and to thereby make it possible to widen the range of application of a poly-p-xylylene film. **SOLUTION:** Tetrafluoro-[2,2]-paracyclophane represented by formula I is obtained by fluorinating diketone-[2,2]-paracyclophane represented by formula III. Tetrafluoro-[2,2]-paracyclophane comprising substantially a pure substance is subjected to decomposition into radicals, polymerization thereof, and vapor deposition on a glass base plate under chemical vapor deposition conditions generally used to give a heat-resistant film of poly- α , α -difluoro-paraxylylene represented by formula II (n is a degree of polymerization). This film has such excellent heat resistance that no exothermic peak due to decomposition will appear up to 550 deg.C in nitrogen in the differential thermal analysis.

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